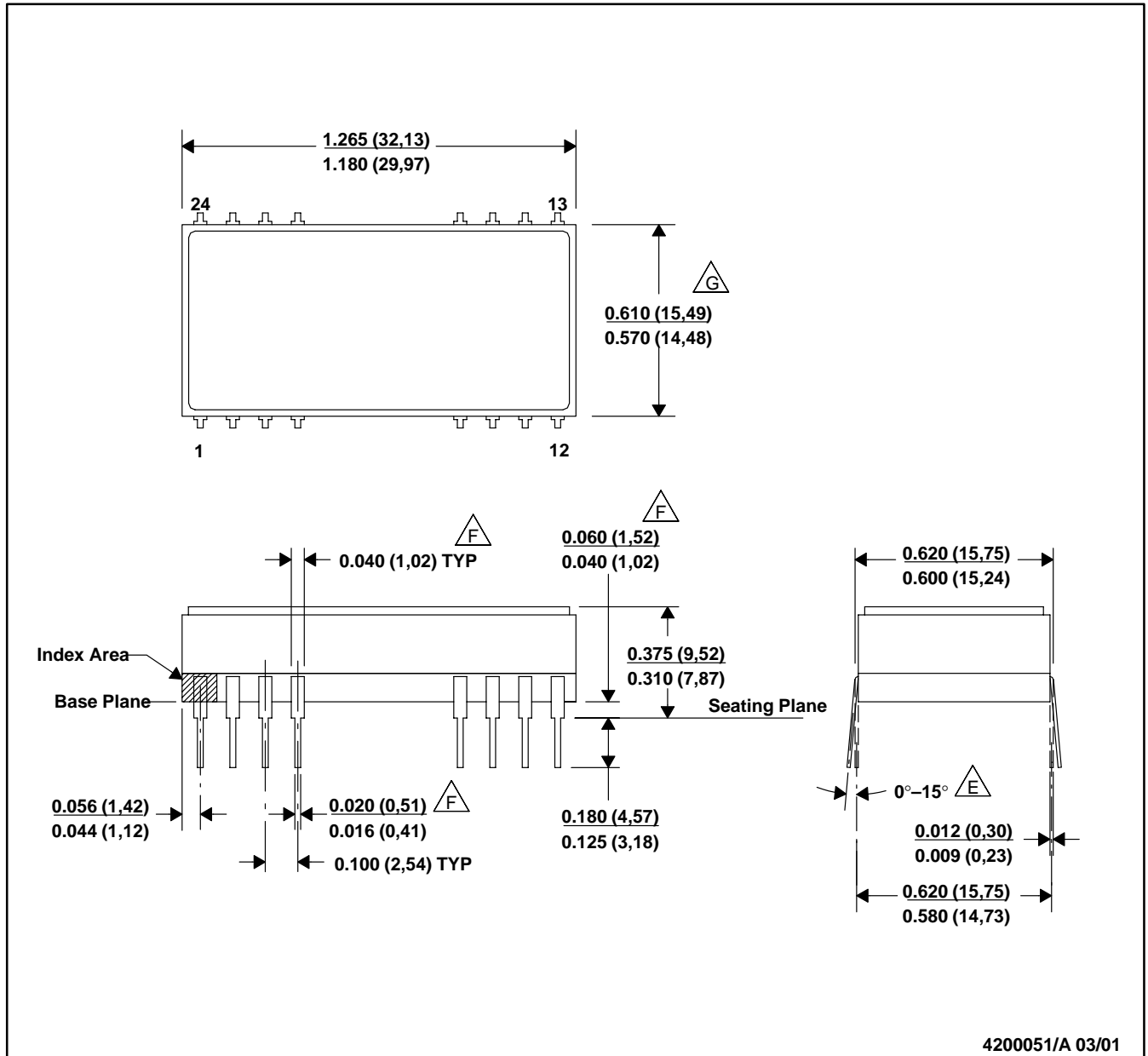


JVB (R-CDIP-T16/24)

CERAMIC SIDE-BRAZE DUAL-IN-LINE



- NOTES: A. All linear dimensions are in inches (millimeters).
 B. This drawing is subject to change without notice.
 C. Controlling dimension: inch
 D. Leads within 0.005 (0,13) radius of true position (TP) at gage plane with maximum material condition and unit installed.
- E** Angle applies at spread leads prior to installation.
- F** Outlines on which the seating plane is coincident with the plane (standoff = 0), terminals lead standoffs are not required, and lead shoulder may equal lead width along any part of the lead above the seating/base plane.
- G** Body width does not include particles of packing materials.
- H. A visual index feature must be located within the cross-hatched area.

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Mailing Address:

Texas Instruments
Post Office Box 655303
Dallas, Texas 75265